



## Product Change Notification: MFOL-15LRFR707

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### Date:

20-May-2025

### Product Category:

Capacitive Touch Sensors

### Notification Subject:

CCB 7549 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected CAP1206-1-SL, CAP1206-1-SL-TR, CAP1206-2-SL-TR, CAP1208-1-SL-TR, CAP1208-2-SL-TR, CAP1296-1-SL-TR, CAP1298-1-SL-TR, CAP1298-2-SL-TR, CAP1208-1-SL, CAP1296-1-SL, and CAP1298-1-SL catalog part numbers (CPN) available in 14L SOIC (.150in) package at MTAI assembly site.

### Affected CPNs:

**MFOL-15LRFR707\_Affected\_CPN\_05202025.pdf**

**MFOL-15LRFR707\_Affected\_CPN\_05202025.csv**

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected CAP1206-1-SL, CAP1206-1-SL-TR, CAP1206-2-SL-TR, CAP1208-1-SL-TR, CAP1208-2-SL-TR, CAP1296-1-SL-TR, CAP1298-1-SL-TR, CAP1298-2-SL-TR, CAP1208-1-SL, CAP1296-1-SL, and CAP1298-1-SL catalog part numbers (CPN) available in 14L SOIC (.150in) package at MTAI assembly site.

### Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand

	(HQ) (MTAI)	(HQ) (MTAI)
<b>Wire Material</b>	Au	CuPdAu
<b>Die Attach Material</b>	8390A	8390A
<b>Molding Compound Material</b>	G600V	G600V
<b>Lead-Frame Material</b>	CDA194	CDA194
<b>Lead-Frame Paddle Size</b>	90 X 90 mm	95 X 155 mm
<b>Lead-Frame DAP Surface Prep</b>	Ag	Bare Cu
<b>Lead-Frame Design</b>	See Pre and Post change summary for comparison.	

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying CuPdAu as a new bond wire material.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** June 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	<b>May 2025</b>					<b>June 2025</b>				
<b>Work Week</b>	18	19	20	21	22	23	24	25	26	27
<b>Initial PCN Issue Date</b>				X						
<b>Qual Report Availability</b>						X				

Final PCN Issue Date						X				
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**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** May 20, 2025: Issued Initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### Attachments:

**PCN\_MFOL-15LRFR707\_Pre and Post Change Summary.pdf**

**PCN\_MFOL-15LRFR707\_Qual\_Plan.pdf**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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